

C5020

Conductor

Description

C5020 is an unfritted lead, gold conductor. It is designed for application on top of a gold-based layer to increase thickness and solderability. In a single print and fire application on a gold base layer it yields a thick, dense film that is free from blisters, cracks, and other cosmetic defects. C5020 has good adhesion when printed over a gold base layer of Heraeus Au conductors. It is not designed to be used without a gold base layer.

Key Features

- Excellent choice for higher conductivity applications that require thick gold conductor



This picture does not show the packaging of C5020 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

| | |
|--------------|--|
| Conductivity | ≤ 4.5 milliohms/square (FFT: 8 μm) |
| Viscosity | 35 – 55 Pas (25 °C, D = 75/s) |
| Alloy Ratio | 100 |
| Coverage | Approx. 50 cm ² / g (FFT: 8 μm) |
| Metal | Au |

Recommended Processing Guide

| | |
|---------------------------|--|
| Printing Parameters | Print through a 200 – 325 mesh stainless steel screen. Level at room temperature for 10 minutes. |
| Printing Speed | Up to at least 10 cm / s |
| Drying Temperature | Dry at 125 – 150 °C for 10 – 20 minutes. |
| Process Temperature (TDS) | Fire at 550 – 950 °C (peak) for 10 minutes, and with a total firing cycle time of c. 30 – 60 minutes |
| Film Thickness | 6 – 10 μm |
| Recommended Thinner | HVS-100 |

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Warranty

6 months

Storage

Store in a dry location at 5°C-25°C

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